

General Description

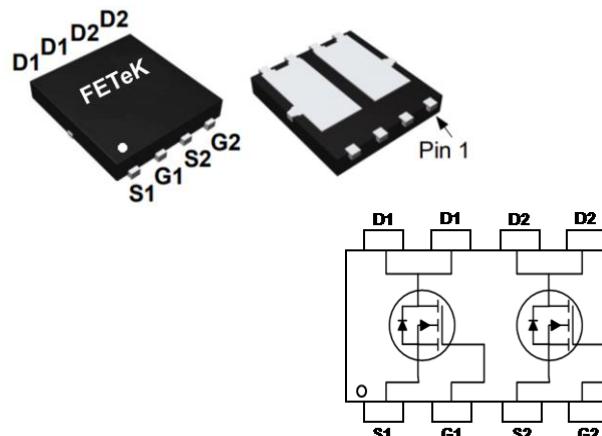
- Advanced Trench MOS Technology
- 100% EAS Guaranteed
- Fast Switching Speed
- Green Device Available

Product Summary

BVDSS	RDS(ON)	ID
100V	20mΩ	28.5A

Applications

- Portable Equipment.
- Battery Powered Systems.
- Hard Switching and High-Speed Circuit.

PRPAK5X6 Pin Configuration**Absolute Maximum Ratings**

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	100	V
V_{GS}	Gate-Source Voltage	± 20	V
$I_D @ T_c = 25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	28.5	A
$I_D @ T_c = 100^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	18.1	A
$I_D @ T_A = 25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	11	A
$I_D @ T_A = 70^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	8.9	A
I_{DM}	Pulsed Drain Current ²	80	A
EAS	Single Pulse Avalanche Energy ³	45	mJ
I_{AS}	Avalanche Current	30	A
$P_D @ T_c = 25^\circ C$	Total Power Dissipation ⁴	29.8	W
$P_D @ T_c = 100^\circ C$	Total Power Dissipation ⁴	11.9	W
$P_D @ T_A = 25^\circ C$	Total Power Dissipation ⁴	2	W
$P_D @ T_A = 70^\circ C$	Total Power Dissipation ⁴	1.3	W
T_{STG}	Storage Temperature Range	-55 to 150	°C
T_J	Operating Junction Temperature Range	-55 to 150	°C

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-Ambient ¹	---	62	°C/W
$R_{\theta JC}$	Thermal Resistance Junction-Case ¹	---	4.2	°C/W



FETek Technology Corp.

FKBA0256

Dual N-Ch 100V Fast Switching MOSFETs

Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$\text{V}_{\text{GS}}=0\text{V}$, $\text{I}_D=250\mu\text{A}$	100	---	---	V
$\text{R}_{\text{DS(ON)}}$	Static Drain-Source On-Resistance ²	$\text{V}_{\text{GS}}=10\text{V}$, $\text{I}_D=10\text{A}$	---	16.5	20	$\text{m}\Omega$
		$\text{V}_{\text{GS}}=4.5\text{V}$, $\text{I}_D=10\text{A}$	---	22	30	
$\text{V}_{\text{GS(th)}}$	Gate Threshold Voltage	$\text{V}_{\text{GS}}=\text{V}_{\text{DS}}$, $\text{I}_D=250\mu\text{A}$	1.2	1.8	2.2	V
I_{DSS}	Drain-Source Leakage Current	$\text{V}_{\text{DS}}=80\text{V}$, $\text{V}_{\text{GS}}=0\text{V}$, $\text{T}_J=25^\circ\text{C}$	---	---	1	uA
		$\text{V}_{\text{DS}}=80\text{V}$, $\text{V}_{\text{GS}}=0\text{V}$, $\text{T}_J=55^\circ\text{C}$	---	---	5	
I_{GSS}	Gate-Source Leakage Current	$\text{V}_{\text{GS}}=\pm 20\text{V}$, $\text{V}_{\text{DS}}=0\text{V}$	---	---	± 100	nA
R_g	Gate Resistance	$\text{V}_{\text{DS}}=0\text{V}$, $\text{V}_{\text{GS}}=0\text{V}$, $f=1\text{MHz}$	---	0.8	---	Ω
Q_g	Total Gate Charge	$\text{V}_{\text{DS}}=50\text{V}$, $\text{V}_{\text{GS}}=10\text{V}$, $\text{I}_D=10\text{A}$	---	17.9	---	nC
Q_{gs}	Gate-Source Charge		---	2.8	---	
Q_{gd}	Gate-Drain Charge		---	5.2	---	
$\text{T}_{\text{d(on)}}$	Turn-On Delay Time	$\text{V}_{\text{DD}}=30\text{V}$, $\text{V}_{\text{GS}}=10\text{V}$, $\text{R}_G=6\Omega$, $\text{I}_D=1\text{A}$	---	13	---	ns
T_r	Rise Time		---	6	---	
$\text{T}_{\text{d(off)}}$	Turn-Off Delay Time		---	30	---	
T_f	Fall Time		---	29	---	
C_{iss}	Input Capacitance	$\text{V}_{\text{DS}}=50\text{V}$, $\text{V}_{\text{GS}}=0\text{V}$, $f=1\text{MHz}$	---	849	---	pF
C_{oss}	Output Capacitance		---	185	---	
C_{rss}	Reverse Transfer Capacitance		---	8	---	

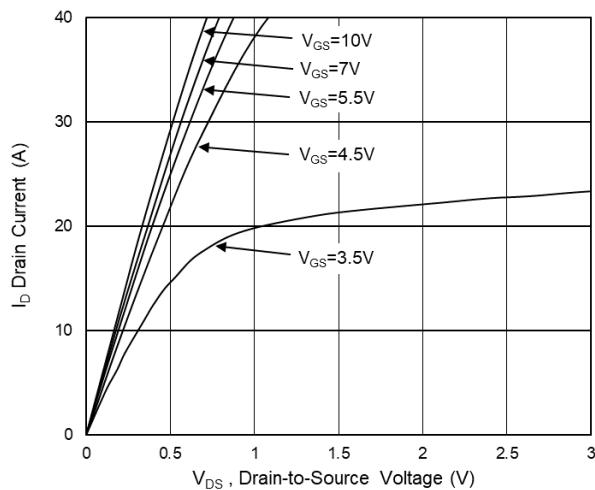
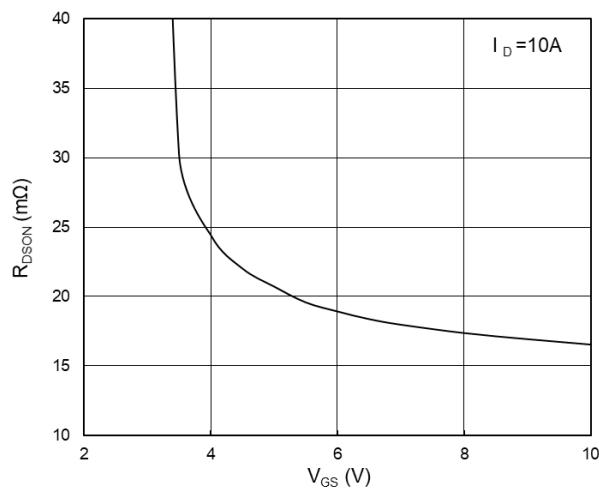
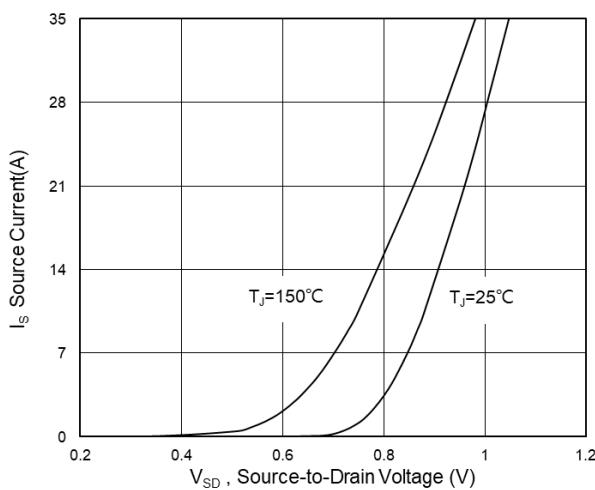
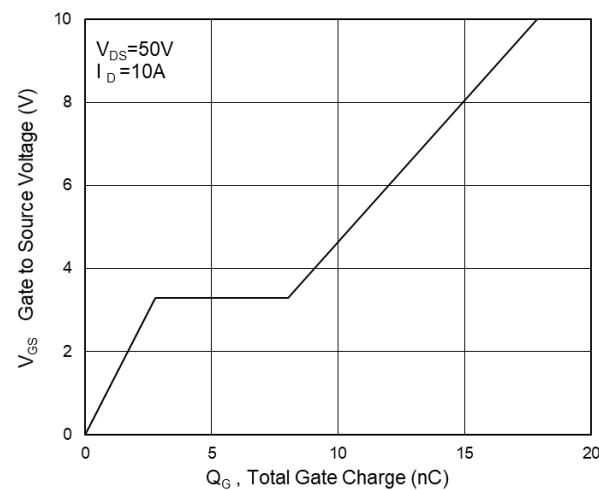
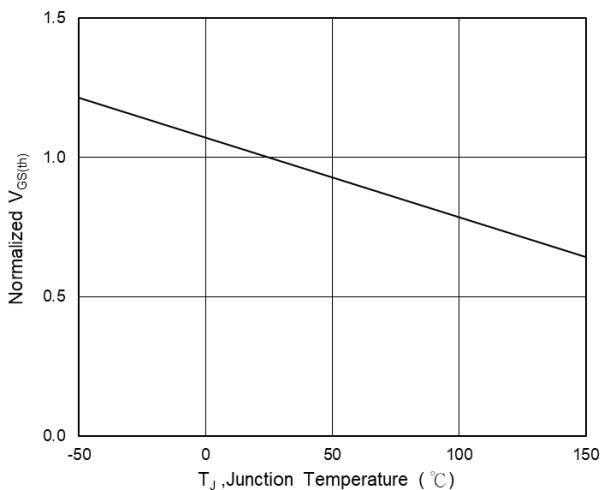
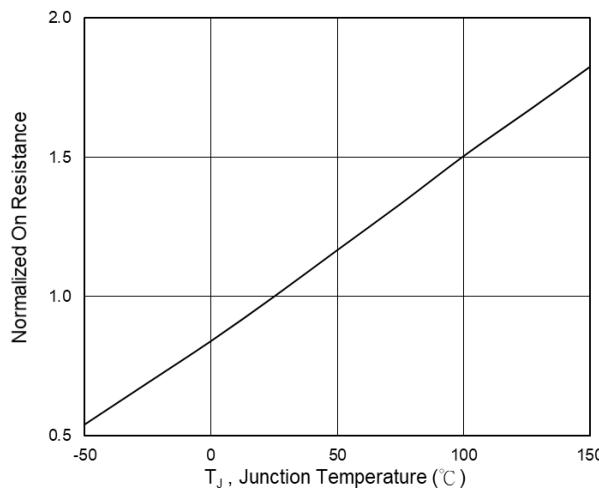
Diode Characteristics

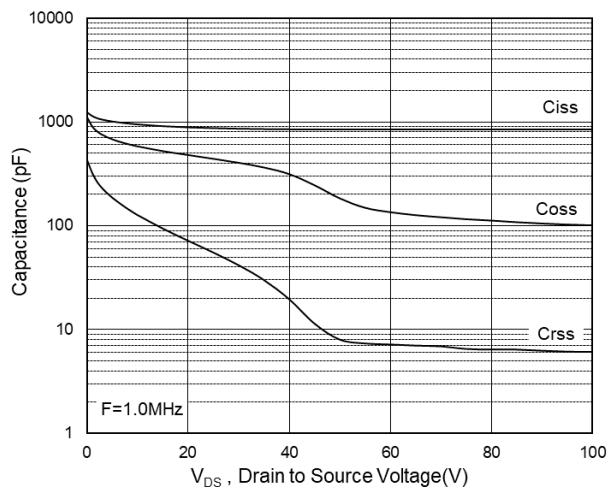
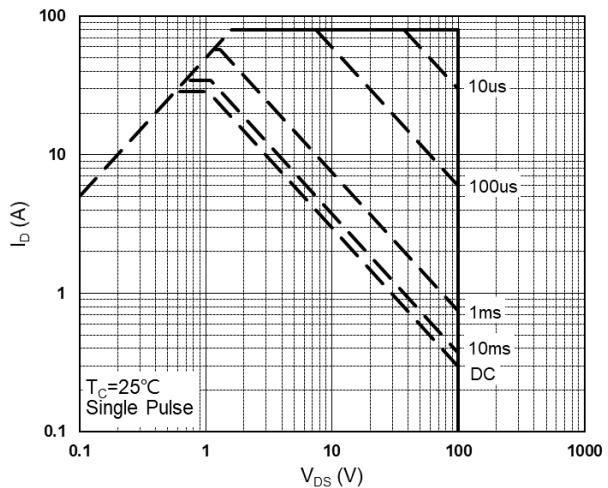
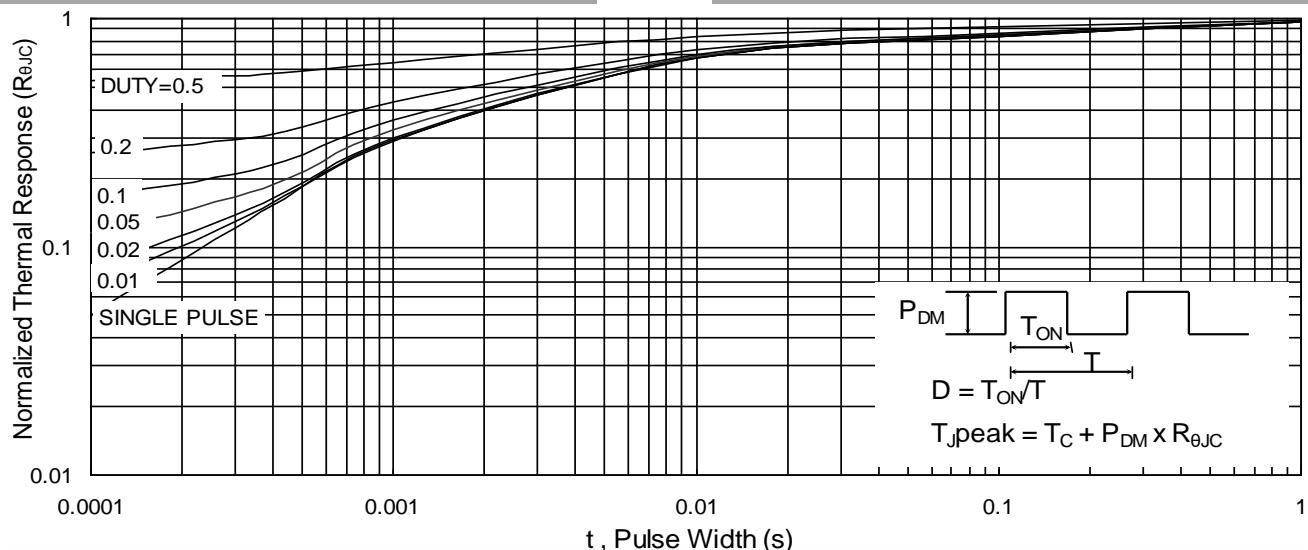
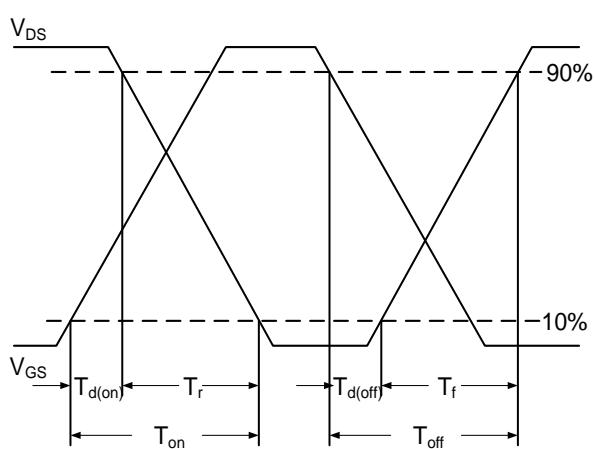
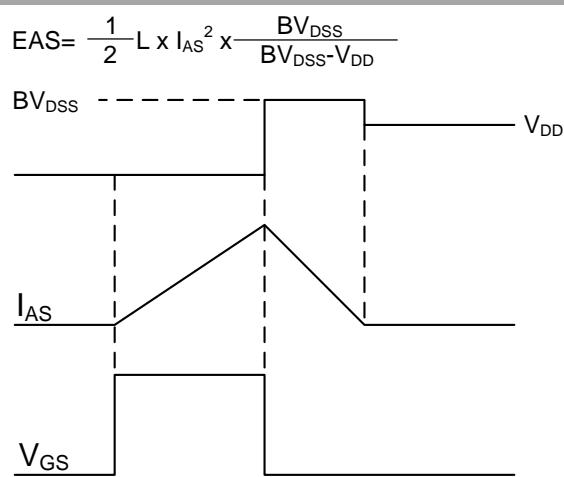
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_s	Continuous Source Current ^{1,6}	$\text{V}_G=\text{V}_D=0\text{V}$, Force Current	---	---	28.5	A
V_{SD}	Diode Forward Voltage ²	$\text{V}_{\text{GS}}=0\text{V}$, $\text{I}_s=1\text{A}$, $\text{T}_J=25^\circ\text{C}$	---	---	1.2	V

Note :

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is $\text{V}_{\text{DD}}=25\text{V}$, $\text{V}_{\text{GS}}=10\text{V}$, $L=0.1\text{mH}$, $\text{I}_{\text{AS}}=30\text{A}$
- 4.The power dissipation is limited by 150°C junction temperature
- 5.The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

Typical Characteristics


Fig.1 Typical Output Characteristics

Fig.2 On-Resistance vs G-S Voltage

Fig.3 Source Drain Forward Characteristics

Fig.4 Gate-Charge Characteristics

Fig.5 Normalized $V_{GS(th)}$ vs T_J

Fig.6 Normalized $R_{DS(on)}$ vs T_J


Fig.7 Capacitance

Fig.8 Safe Operating Area

Fig.9 Normalized Maximum Transient Thermal Impedance

Fig.10 Switching Time Waveform

Fig.11 Unclamped Inductive Switching Waveform